

# 16A, 650V SiC Merged PIN Schottky Diode

#### **FEATURES**

- Max junction temperature 175°C
- MPS structure for high ruggedness to forward current surge events
- High-speed switching possible
- High forward surge capability
- High-frequency operation
- Positive temperature coefficient on V<sub>F</sub>
- RoHS compliant
- Halogen-free

			 $\sim$	~ .
$\Delta \mathbf{L}$	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	.IC#		M 🤝

- General purpose
- Switch mode power supplies
- Power factor correction

#### **MECHANICAL DATA**

• Case: TO-247-3L

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

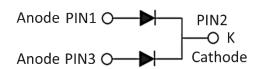
• Polarity: As circuit diagram • Weight: 6.28g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
l <sub>F</sub>	16	Α		
$V_{RRM}$	650	V		
I <sub>FSM</sub>	68	Α		
T <sub>J MAX</sub>	175	°C		
Package	TO-247-3L			
Configuration	Common cathode			









PARAMETER	SYMBOL	VALUE	UNIT	
Repetitive peak reverse voltage		V <sub>RRM</sub>	650	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	455	V	
Continuous Rectified Forward Current @ T <sub>J</sub> = 159°C per leg / per device		lF	8 / 16	А
Surge peak forward current 10ms single half	$T_C = 25^{\circ}C$		68	А
sine-wave superimposed on rated load	T <sub>C</sub> = 125°C	IFSM	56	А
Junction temperature		ΤJ	-55 to +175	°C
Storage temperature		T <sub>STG</sub>	-55 to +175	°C



# Taiwan Semiconductor

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TYP	MAX	UNIT
Junction-to-case thermal resistance per leg	Rejc	1.23	1.48	°C/W

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
	I <sub>F</sub> = 4A, T <sub>J</sub> = 25°C	VF	1.14	-	V
	I <sub>F</sub> = 8A, T <sub>J</sub> = 25°C		1.33	1.45	V
Forward voltage per log(1)	I <sub>F</sub> = 4A, T <sub>J</sub> = 150°C		1.68	-	V
Forward voltage per leg <sup>(1)</sup>	I <sub>F</sub> = 8A, T <sub>J</sub> = 150°C		1.52	-	V
	I <sub>F</sub> = 4A, T <sub>J</sub> = 175°C		1.20	-	V
	I <sub>F</sub> = 8A, T <sub>J</sub> = 175°C		1.60	1.85	V
Reverse current @ rated V <sub>R</sub> per leg <sup>(2)</sup>	T <sub>J</sub> = 25°C	l <sub>R</sub>	-	20	μA
	T <sub>J</sub> = 175°C	IR IR	-	200	μA
	$f = 1MHz, V_R = 1V$		389	-	pF
Junction capacitance per leg	$f = 1MHz, V_R = 200V$	CJ	62.0	-	pF
	f = 1MHz, V <sub>R</sub> = 400V		41.5	-	pF
Capacitive Charge per leg	V <sub>R</sub> = 400V	Qc	29.2	-	nC

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE	PACKAGE	PACKING		
TSCDH16065G1	TO-247-3L	30 / Tube		



#### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.1 Typical Forward Characteristics

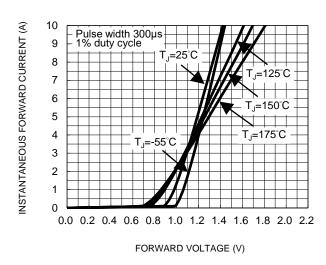


Fig.3 Peak forward current versus case temperature

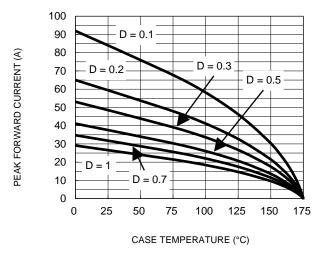


Fig.5 Typical Capacitive Charge

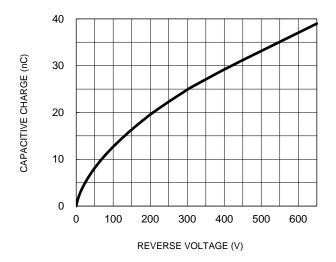


Fig.2 Typical Reverse Characteristics

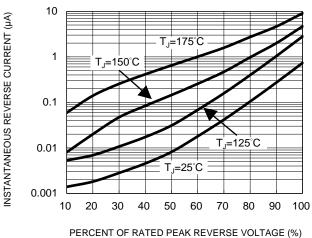


Fig.4 Typical Junction Capacitance

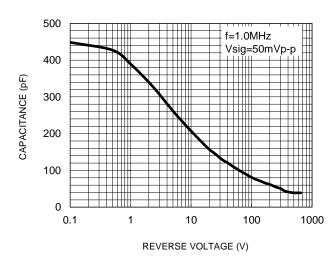
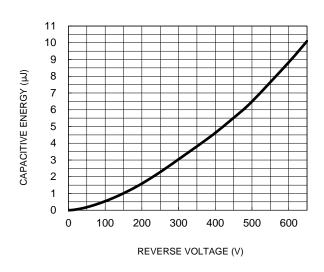


FIG.6 Typical Capacitance Stored Energy

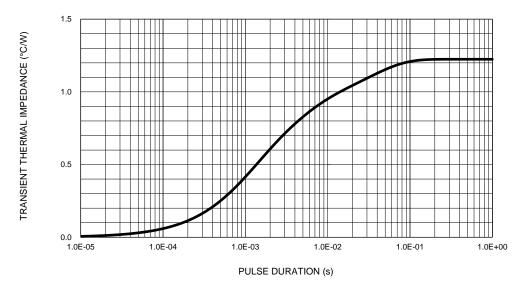




## **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

**Fig.7 Typical Transient Thermal Characteristics** 

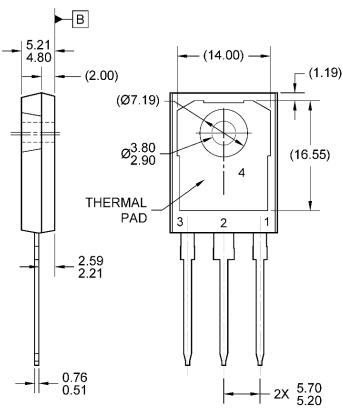


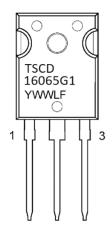


#### **PACKAGE OUTLINE DIMENSIONS**

# 16.40 Α 15.50 2.75 2.16 6.20 5.39 21.30 4 5.49 4.32 4.40 3.50 20.32 19.62 2X 2.39 1.91 3X 1.36 1.11 3.22 <del>♦</del> 0.254**M** B A**M**

# TO-247-3L





### MARKING DIAGRAM

= YEAR CODE

WW = WEEK CODE (01~52)

= LOT CODE (1~9, A~Z)

F = FACTORY CODE NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC TO-247, VARIATION AD, ISSUE E.

DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.

5. DWG NO. REF: HQ2SD07-TO247ADSiC-122 REV A.



Taiwan Semiconductor

# **Notice**

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.